

ABSTRACT OF THE DISCLOSURE

A semiconductor laser module comprising, a  
semiconductor laser element, an electronic cooling  
element configured to allow heat from the semiconductor  
5 laser element to be transmitted thereto, a heat sink  
configured to allow the heat which is transmitted  
to the electronic cooling element to be released,  
an optical system configured to conduct a laser beam  
which is emitted from the semiconductor laser element  
10 to an optical fiber cable, and a heat resistance  
section configured to transmit the heat of the optical  
system to the electronic cooling element, having a heat  
resistance greater than a heat resistance when the heat  
of the semiconductor laser element is transmitted to  
15 the electronic cooling element.